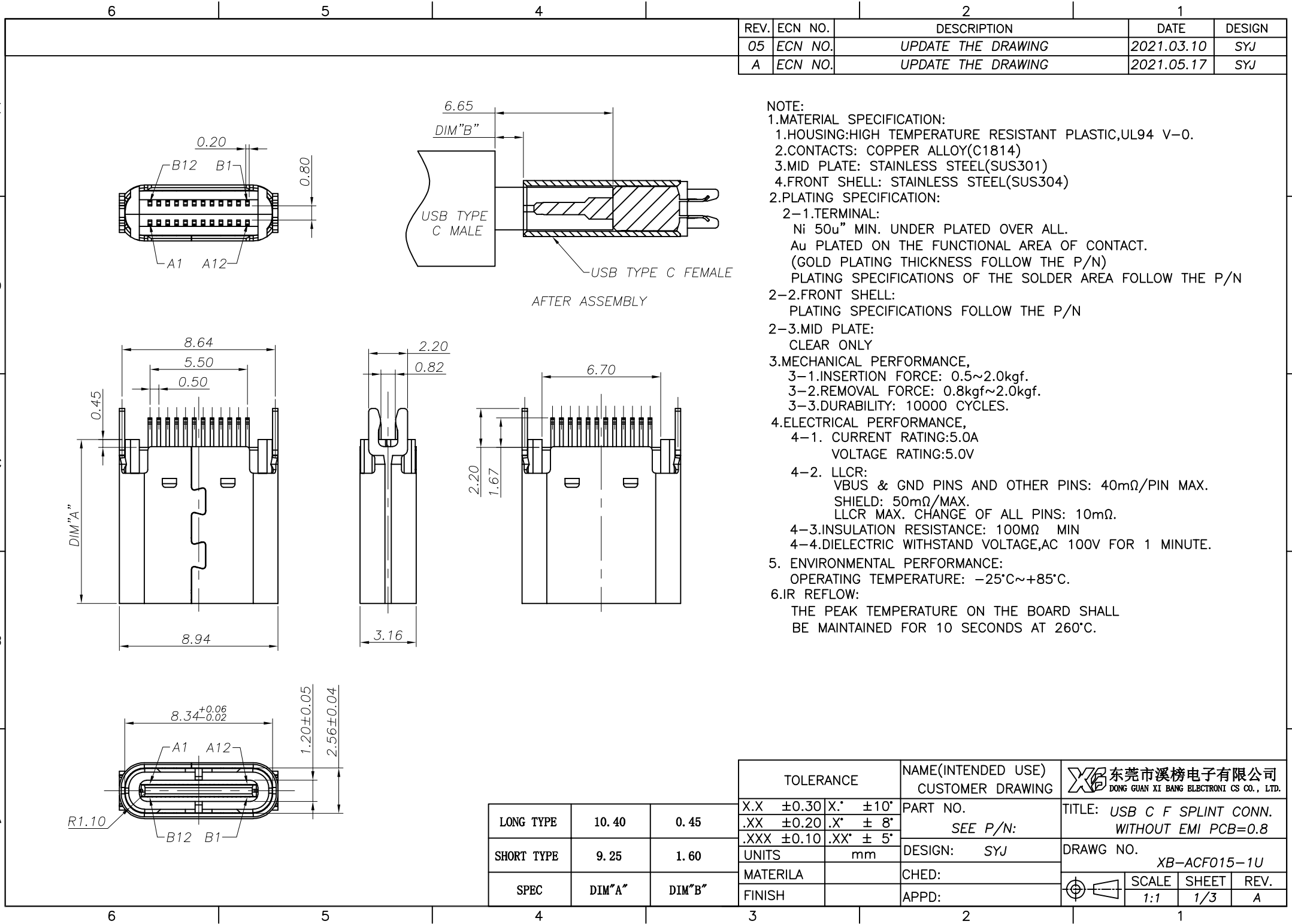




REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
05	ECN NO.	UPDATE THE DRAWING	2021.03.10	SYJ
A	ECN NO.	UPDATE THE DRAWING	2021.05.17	SYJ

NOTE:

1.MATERIAL SPECIFICATION:

1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.

2.CONTACTS: COPPER ALLOY(C1814)

3.MID PLATE: STAINLESS STEEL(SUS301)

4.FRONT SHELL: STAINLESS STEEL(SUS304)

2.PLATING SPECIFICATION:

2-1.TERMINAL:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

PLATING SPECIFICATIONS FOLLOW THE P/N

2-3.MID PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~2.0kgf.

3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.

3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING:5.0A

VOLTAGE RATING:5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

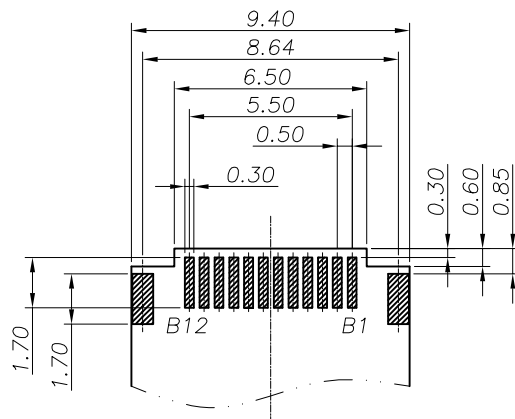
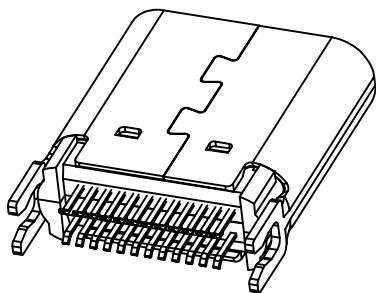
OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

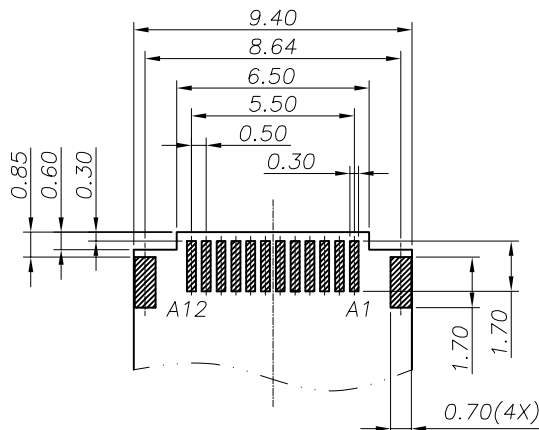
THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

			TOLERANCE		NAME(INTENDED USE) CUSTOMER DRAWING		 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELBCTRONI CS CO., LTD.			
LONG TYPE	10.40	0.45	X.X ±0.30	X.* ±10°	PART NO. SEE P/N:	TITLE: USB C F SPLINT CONN. WITHOUT EMI PCB=0.8				
			.XX ±0.20	.X* ± 8°						
			.XXX ±0.10	.XX* ± 5°						
SHORT TYPE	9.25	1.60	UNITS	mm	DESIGN: SYJ	DRAWG NO. XB-ACF015-1U				
			MATERILA		CHED:					
SPEC	DIM"A"	DIM"B"	FINISH		APPD:		SCALE	SHEET	REV.	
							1:1	1/3	A	

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
05	ECN NO.	UPDATE THE DRAWING	2021.03.10	SYJ
A	ECN NO.	UPDATE THE DRAWING	2021.05.17	SYJ



BOTTOM VIEW



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS 0.8.0±0.05MM;DEFAULT TOLERANCE:±0.05

USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A2	SSTXp1	B11	SSRXp1
A3	SSTXn1	B10	SSRXn1
A4	Vbus	B9	Vbus
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	Vbus	B4	Vbus
A10	SSRXn2	B3	SSTXn2
A11	SSRXp2	B2	SSTXp2
A12	GND	B1	GND

P/N: ACF015-1X1H1A003-XHU

HOUSING MATERIAL

A: LCP
E: PA9T

SPEC

0: SHORT TYPE DIM"A"=9.25
1: LONG TYPE DIM"A"=10.40

CONTACT SOLDER AREA PLATED

0: Sn
1: Au 1u"

CONTACT FUNCTIONAL AREA PLATED

03: Au 3u"
15: Au 15u"
30: Au 30u"

TOLERANCE		NAME(INTENDED USE) CUSTOMER DRAWING	XHB 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONIC CO., LTD.		
X.X ±0.30	X.* ±10*	PART NO.	TITLE: USB C F SPLINT CONN. WITHOUT EMI PCB=0.8		
.XX ±0.20	.X* ± 8*	SEE P/N:			
.XXX ±0.10	.XX* ± 5*	DESIGN: SYJ	DRAWG NO.		
UNITS	mm	CHED:	XB-ACF015-1U		
MATERILA		APPD:			
FINISH					
				SCALE 1:1	SHEET 2/3
				REV. A	

